

(19)



Europäisches Patentamt  
European Patent Office  
Office européen des brevets

(11)

Publication number:

**0 259 163**  
**A3**

(12)

# EUROPEAN PATENT APPLICATION

(21)

Application number: **87307786.1**

(51)

Int. Cl.4: **G01R 1/073 , H05K 13/08**

(22)

Date of filing: **03.09.87**

(30)

Priority: **05.09.86 US 904738**

(43)

Date of publication of application:  
**09.03.88 Bulletin 88/10**

(84)

Designated Contracting States:  
**DE FR GB NL**

(88)

Date of deferred publication of the search report:  
**12.07.89 Bulletin 89/28**

(71)

Applicant: **TEKTRONIX, INC.**  
**Howard Vollum Park 14150 S.W. Karl Braun**  
**Drive P.O. Box 500**  
**Beaverton Oregon 97077(US)**

(72)

Inventor: **Rath, Dale R.**  
**Star Route Box 322A**  
**Gales Creek Oregon 97117(US)**

(74)

Representative: **Burke, Steven David et al**  
**R.G.C. Jenkins & Co. 26 Caxton Street**  
**London SW1H 0RJ(GB)**

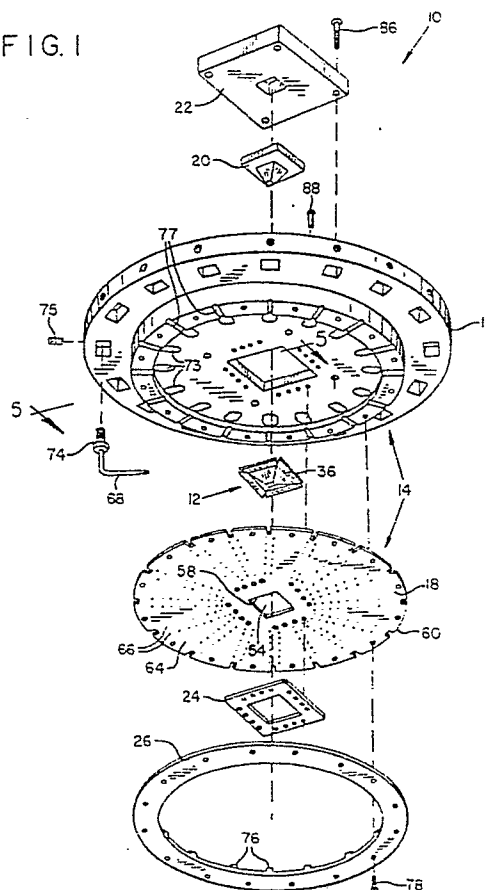
(54)

**Semiconductor wafer probe.**

(57)

A flexible thin film probe head extends below a probe frame and supports a plurality of wafer contact bumps in planar array. An elastic member is positioned between a rigid plate and the surface of the thin film opposite the contact bumps so as to provide a controlled pressure interconnect between the I/O pads on the wafer and the contact bumps. Interface between the contact bumps and external test equipment is made through constant impedance transmission lines on the probe head and on an adjoining substrate. The two sets of transmission lines are coupled together by mechanical pressure contacts so as to facilitate the substitution of other probe heads having different wafer I/O pad configurations. Interface between the transmission lines on the printed circuit board and a set of semirigid coaxial cables is made by a second pressure interface so as to simplify assembly of the unit.

FIG. 1



EP 0 259 163 A3



